

# Chemical content 74HCT10PW

Type number	Package	Package description	Total product weight
74HCT10PW	SOT402-1	TSSOP14	51.84251 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935186270118	10	1	260	30 s	1	240	20 s	3	Suzhou, China; Nijmegen, Netherlands; Bangkok, Thailand	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.03114	77.86000	0.06007
		Polymer	Acrylic resin	Proprietary	0.00607	15.18000
		Resin system	Proprietary	0.00278	6.96000	0.00537
		subTotal		0.04000	100.00000	0.07715
Die	Doped silicon	Silicon (Si)	7440-21-3	0.20320	100.00000	0.39195
		subTotal		0.20320	100.00000	0.39195
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	19.04564	97.47000	36.73749
		Iron (Fe)	7439-89-6	0.46896	2.40000	0.90459
		Phosphorous (P)	7723-14-0	0.00586	0.03000	0.01131
		Zinc (Zn)	7440-66-6	0.01954	0.10000	0.03769
		subTotal		19.54000	100.00000	37.69108
Mould Compound	Additive	Non hazardous	Proprietary	1.48896	4.70000	2.87208
	Filler	Silica fused	60676-86-0	25.02720	79.00000	48.27544
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	1.90080	6.00000	3.66649
	Pigment	Carbon black	1333-86-4	0.06336	0.20000	0.12222
	Polymer	1.4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	1.26720	4.00000	2.44433
		Non hazardous	Proprietary	1.29888	4.10000	2.50543
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.63360	2.00000	1.22216
	subTotal		31.68000	100.00000	61.10815	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.00290	1.00000	0.00559
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.28130	97.00000	0.54260
		Palladium (Pd)	7440-05-3	0.00580	2.00000	0.01119
		subTotal		0.29000	100.00000	0.55938
Wire	Pure metal	Copper (Cu)	7440-50-8	0.08931	100.00000	0.17227
		subTotal		0.08931	100.00000	0.17227

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